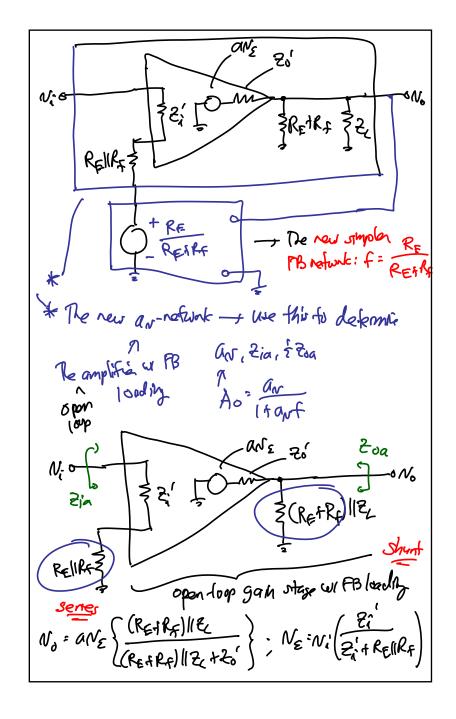
Lecture 27: Feedback Inspection Announcements: \$Lab#3 (your project) due on Friday, May 6, at 5 p.m. \$ Passed out Feedback Inspection Handout \$ Passed out Final Information Sheet and sample Final Exam (from 2009) · Lecture Topics: ♦ Open-Loop Amp w/ Feedback Loading \$Final Exam Info & Course Wrap Up Last Time: Open-Loop Amp w/ Feedback Loading \$*5*{ 24 Next Stage Impedance RELIRE 3 REARED RE



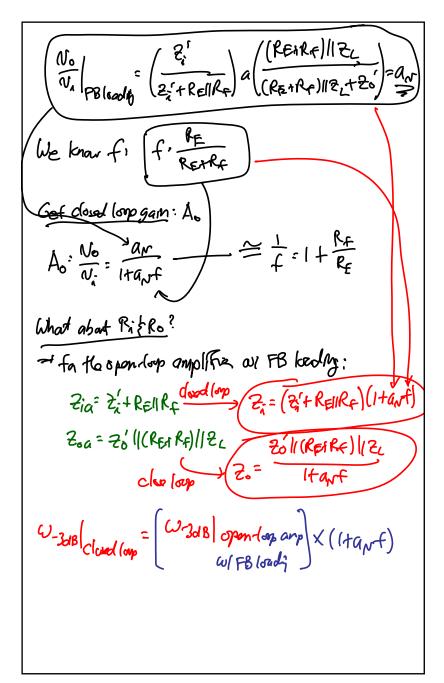
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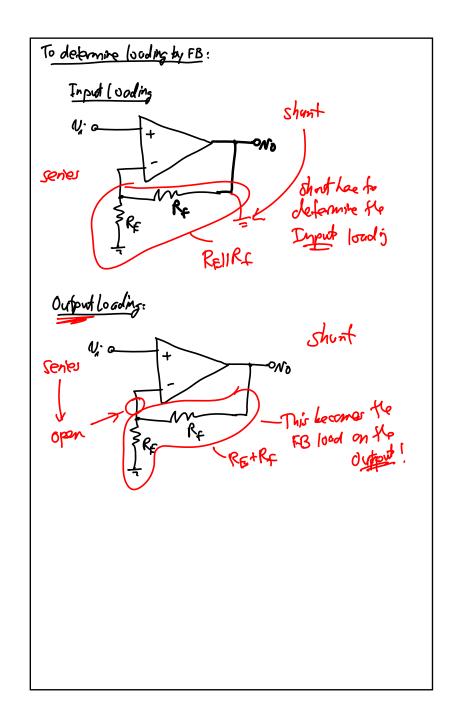
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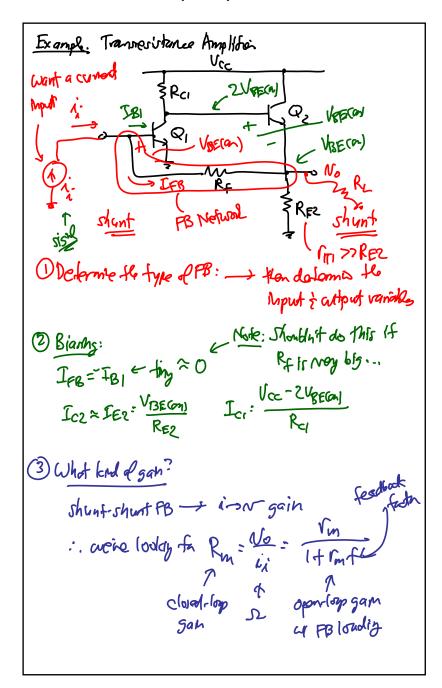
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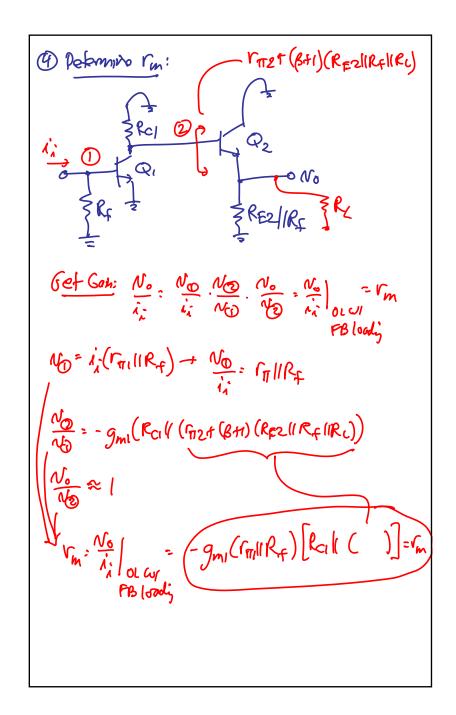
<u>EE 140</u>: Analog Integrated Circuits <u>Lecture 27w</u>: Feedback By Inspection



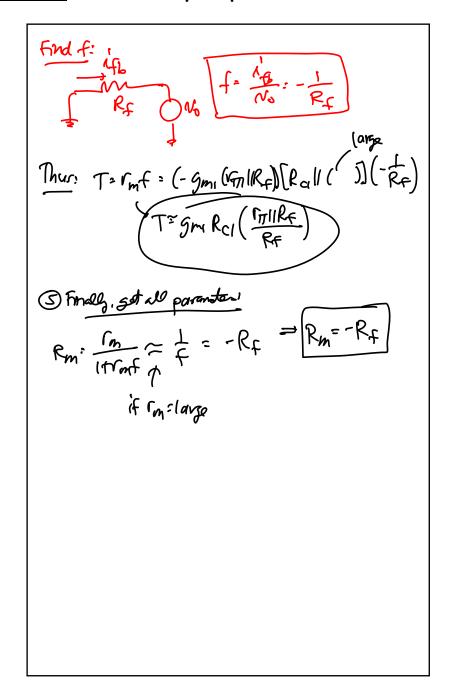


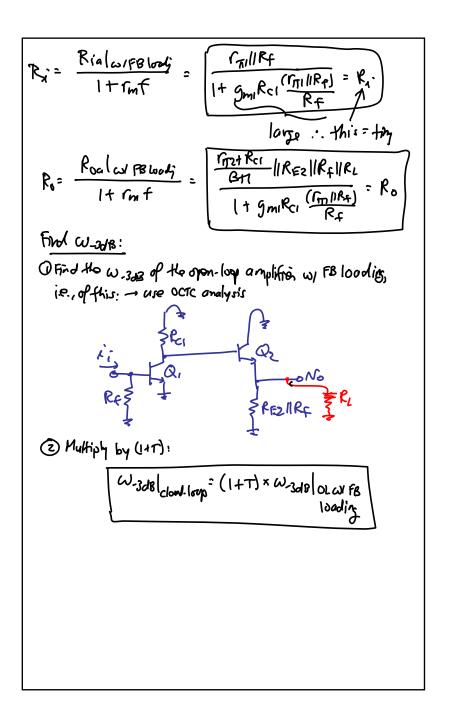
EE 140: Analog Integrated Circuits Lecture 27w: Feedback By Inspection





EE 140: Analog Integrated Circuits Lecture 27w: Feedback By Inspection





- What's next?
- · EE 240: Advanced Analog Integrated Circuits
- Analysis and optimized design of integrated analog systems and building blocks. Specific topics include operational and wide-band amplifiers, gainbandwidth and power considerations, analysis of noise in integrated circuits, low noise design, feedback, precision passive elements, analog switches, comparators, CMOS voltage references, non-idealities such as matching and supply/IO/substrate coupling. The course will include a significant design project applying the techniques taught in class to implement the analog front-end of a high-speed serial link.
- EE 142: Integrated Circuits for Communication
- Analysis and design of electronic circuits for communication systems, with an emphasis on integrated circuits for wireless communication systems. Analysis of noise and distortion in amplifiers with application to radio receiver design. Power amplifier design with application to wireless radio transmitters. Radio-frequency mixers, oscillators, phase-locked loops, modulators, and demodulators.
- · EE C245: Introduction to MEMS
- Physics, fabrication, and design of microelectromechanical systems (MEMS). Micro and nanofabrication processes, including silicon surface and bulk micromachining and non-silicon micromachining. Integration strategies and assembly processes. Transduction strategies and mechanical circuits. Electronic position-sensing circuits and electrical and mechanical noise. CAD for MEMS. Design project is required.